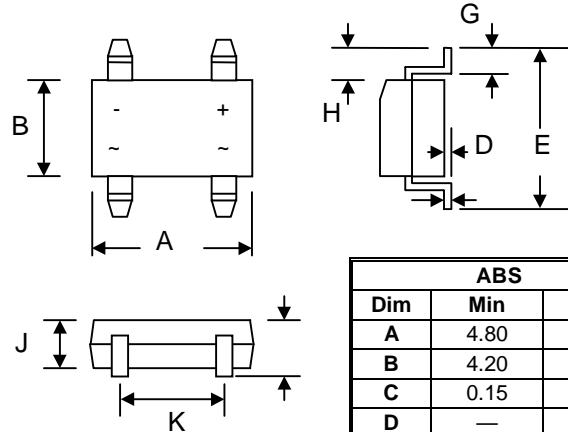


Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- High Surge Current Capability
- For Use in Low Voltage Application
- Plastic Case Material has UL Flammability Classification Rating 94V-O



ABS		
Dim	Min	Max
A	4.80	5.30
B	4.20	4.60
C	0.15	0.25
D	—	0.20
E	6.00	6.80
G	0.30	0.70
H	0.90	1.10
J	—	1.50
K	3.80	4.20
L	1.22	1.72
All Dimensions in mm		

Mechanical Data

- Case: SOPA-4, ABS, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Mounting Position: Any
- Marking: Type Number
- **Lead Free: For RoHS / Lead Free Version**

Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	KABS 12	KABS 13	KABS 14	KABS 15	KABS 16	KABS 18	KABS 110	KABS 115	KABS 120	KABS 125	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	20	30	40	50	60	80	100	150	200	250	V	
RMS Reverse Voltage	$V_R(\text{RMS})$	14	21	28	35	42	56	70	105	140	175	V	
Average Rectified Output Current @ $T_L = 90^\circ\text{C}$	I_O	1.0										A	
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30										A	
Forward Voltage @ $I_F = 1.0\text{A}$	V_{FM}	0.50			0.70		0.85		0.90		0.92	V	
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^\circ\text{C}$	I_{RM}	0.1						20					mA
Typical Thermal Resistance (Note 1)	$R_{\theta JL}$ $R_{\theta JA}$	10						50					$^\circ\text{C/W}$
Typical Junction Capacitance	C_j	110					30		110				pF
Operating Temperature Range	T_j	-65 to +150										$^\circ\text{C}$	
Storage Temperature Range	T_{STG}	-65 to +150										$^\circ\text{C}$	

Note: 1. Mounted on P.C. Board with 5.0mm² copper pad area.